

April 2014

FQA40N25

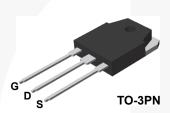
N-Channel QFET $^{\rm @}$ MOSFET 250 V, 40 A, 70 m Ω

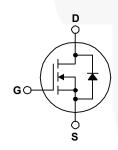
Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

- 40 A, 250 V, $R_{DS(on)}$ = 70 m Ω (Max.) @ V_{GS} = 10 V, I_D = 20 A
- Low Gate Charge (Typ. 85nC)
- Low Crss (Typ. 70pF)
- 100% Avalanche Tested





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQA40N25	Unit	
V _{DSS}	Drain-Source Voltage		250	V	
I _D	Drain Current - Continuous (T _C = 25°C	C)	40	Α	
	- Continuous (T _C = 100°C)		25	Α	
I _{DM}	Drain Current - Pulsed	(Note 1)	160	Α	
V _{GSS}	Gate-Source Voltage		± 30	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	800	mJ	
I _{AR}	Avalanche Current	(Note 1)	40	Α	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	28	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns	
P_{D}	Power Dissipation (T _C = 25°C)		280	W	
	- Derate above 25°C		2.22	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	FQA40N25	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case , Max.	0.45	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink , Typ.	0.24	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient , Max.	40	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQA40N25	FQA40N25	TO-3PN	Tube	N/A	N/A	30 units

Electrical Characteristics T_c = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Cha	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	250			V
ΔBV_{DSS} / ΔT_{J}	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.24		V/°C
I _{DSS}	Zana Cata Valta na Duais Comunant	V _{DS} = 250 V, V _{GS} = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 200 V, T _C = 125°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 20 A		0.051	0.07	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 20 A	\-	29		S
	ic Characteristics					
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,		3100	4000	pF
C _{oss}	Output Capacitance	f = 1.0 MHz		620	800	pF
C _{rss}	Reverse Transfer Capacitance			70	90	pF
Switchi	ing Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 125 V, I _D = 40 A,		70	150	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$		580	1150	ns
t _{d(off)}	Turn-Off Delay Time			120	250	ns
t _f	Turn-Off Fall Time	(Note 4)		165	340	ns
Qg	Total Gate Charge	V _{DS} = 200 V, I _D = 40 A,		85	110	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V		25		nC
Q _{gd}	Gate-Drain Charge	(Note 4)	/	46		nC
	ource Diode Characteristics a	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Diode Forward Current				40	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				160	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 40 A			1.5	V
t _{rr}	Reverse Recovery Time			220		ns
Q _{rr}	Reverse Recovery Charge	dl _F / dt = 100 A/μs		2.0	//	μС

- **Notes:** 1. Lepetitive Rating: Pulse width limited by maximum junction temperature 2. L = 0.8 mH, I_{AS} = 40 A, V_{DD} = 50 V, R_G = 25 Ω , Starting T_J = 25°C 3. $I_{SD} \le 40$ A, di/dt ≤ 300 A/ μ s, $V_{DD} \le BV_{DSS}$, Starting T_J = 25°C 4. Essentially independent of operating temperature

Typical Characteristics

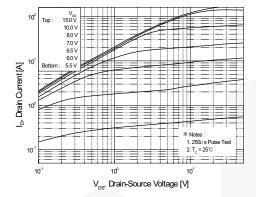


Figure 1. On-Region Characteristics

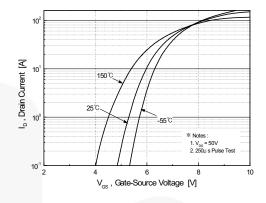


Figure 2. Transfer Characteristics

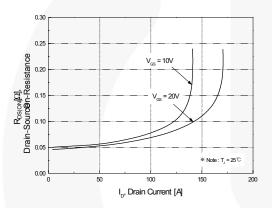


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

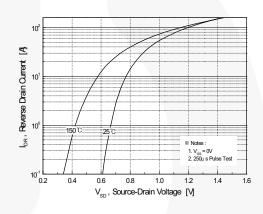


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

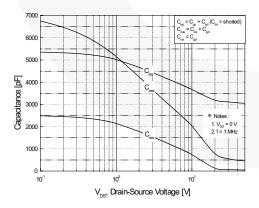


Figure 5. Capacitance Characteristics

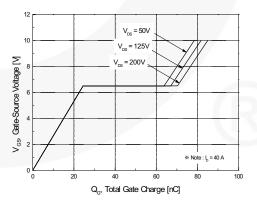


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

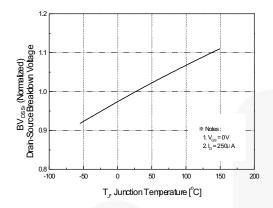


Figure 7. Breakdown Voltage Variation vs. Temperature

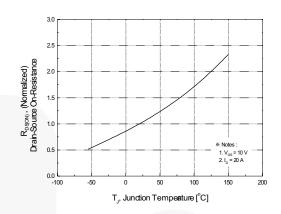


Figure 8. On-Resistance Variation vs. Temperature

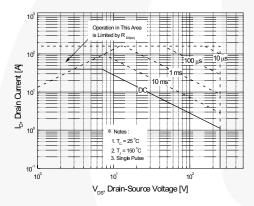


Figure 9. Maximum Safe Operating Area

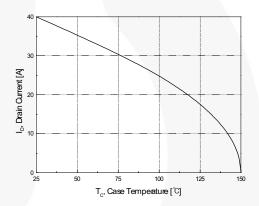


Figure 10. Maximum Drain Current vs. Case Temperature

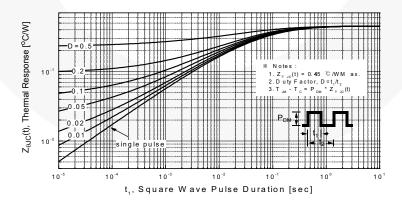


Figure 11. Transient Thermal Response Curve

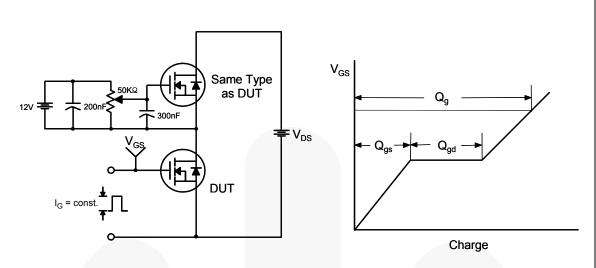


Figure 12. Gate Charge Test Circuit & Waveform

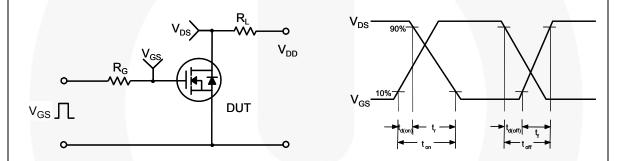


Figure 13. Resistive Switching Test Circuit & Waveforms

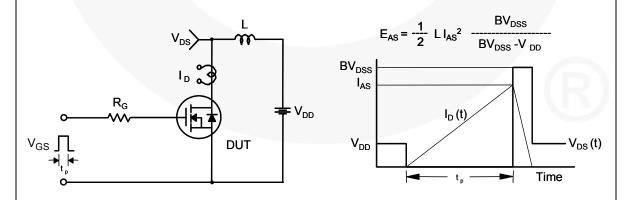
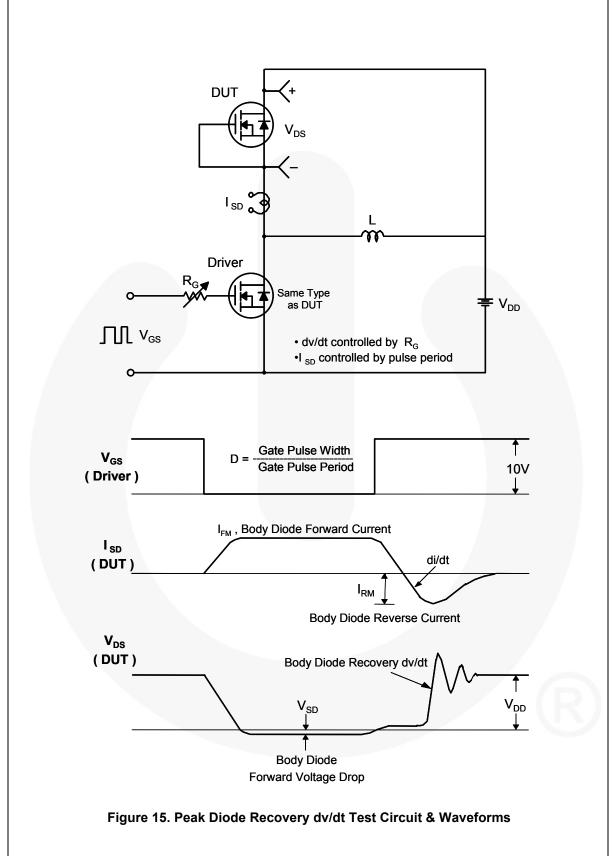
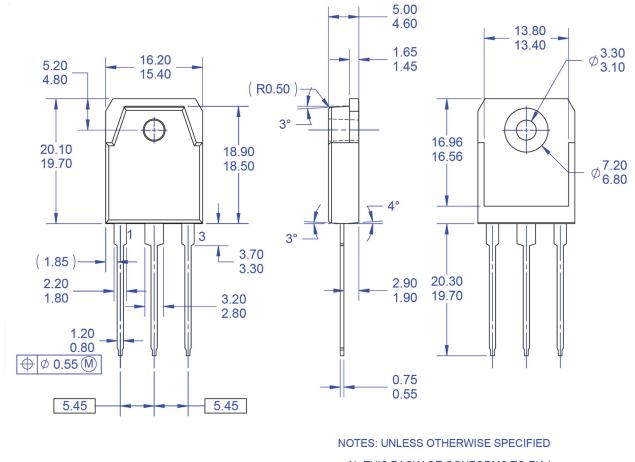
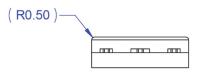


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions





- A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- **DIMENSION AND TOLERANCING PER** ASME14.5-2009.
- D) DIMENSIONS ARE EXCLUSSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSSIONS.
 E) DRAWING FILE NAME: TO3PN03AREV1.
- FAIRCHILD SEMICONDUCTOR.

Figure 16. TO3PN, 3-Lead, Plastic, EIAJ SC-65

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